

L Number	Hits	Search Text	DB	Time stamp
1	3543	silicide same alloy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 17:49
8	28331	(spatter\$4 sputter\$4 deposit\$3) near4 (alloy silicide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 17:52
15	8198	((spatter\$4 sputter\$4 deposit\$3) near4 (alloy silicide)) and (438/\$.ccls. 257/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 17:52
22	22117	(spatter\$4 sputter\$4 deposit\$3) near4 (alloy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 17:52
29	396	((spatter\$4 sputter\$4 deposit\$3) near4 (alloy)) same (silicide salicide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 17:56
36	270	((spatter\$4 sputter\$4 deposit\$3) near4 (alloy)) same (silicide salicide)) and (438/\$.ccls. 257/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 17:56
43	160	((spatter\$4 sputter\$4 deposit\$3) near4 (alloy)) near15 (silicide salicide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 17:56
50	94	((spatter\$4 sputter\$4 deposit\$3) near4 (alloy)) near15 (silicide salicide)) and (438/\$.ccls. 257/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 18:06
57	10443	(anneal\$4 heat\$4 bak\$4 thermal thermally) near20 (silicide salicide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 18:07
64	87	((spatter\$4 sputter\$4 deposit\$3) near4 (alloy)) same ((anneal\$4 heat\$4 bak\$4 thermal thermally) near20 (silicide salicide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/27 18:08